

# In-Line 3D Automatic Optical Inspection systems

True 3D imaging, Side cameras integrated in 3D processing. Revolutionary 3D imaging technology The latest generation of high speed, high quality cameras High Speed 90Fps USB 3 Vision Cameras No capture card requirements. 2X FOV over previous Generation Multi-color 4 angle lighting with Line Source Coaxial Lighting and Meniscus Profiler Inspects: Components: SMT & THT (missing, type, polarity, offset, text, colors, etc.) Component Height and Coplanarity Solder Paste and CIP (Components in Paste; pre-reflow) Soldering: Post Reflow, Post Wave, Selective, Manual

GTAZ

Up to 50% reduction of cycle time. reliable solder joint meniscus and pad surface analysis (to find meniscus and paste printing defects) use inspection in all stages of the production process Flexible classification and reporting scenarios..... Line Sourced DOAL (Direct On Axis Lighting) coaxial lighting inspect solder joints without shadow effects from tall system with high resolution Telecentric Optics..... find defects easier including printing defects on Gold or Cu Low Noise Large CCD High Speed 24 bit Color Camera plated PCB's powerful algorithms to achieve an optimal balance between Synthetic Imaging and Spectral Analysis..... defect detection and false reject levels in shortest time Use for automatic inspection, classification and repair Triple use of side camera's program in minutes to verify your production line is set-up Prototype mode for 1st off inspection..... correctly before starting full production Compensate for PCB warp and adapt to tall component and In height adjustable optical head

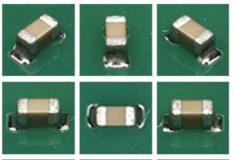
integrate AOI efficiently in your existing operations and factory

components nearby and accurate inspection model building

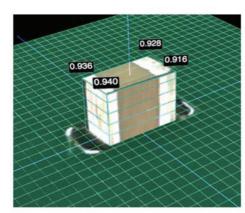


# Enwertpeckar GTAZ

# **Hardware and Software Features**



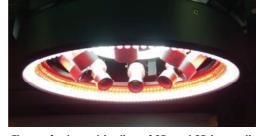




### Revolutionary 3D imaging

True Stereoscopic imaging using 9 cameras. Full colour 3D allows the ability to actually see the side of components rather than extruded 2D images. Using the addition of a 4th LED white light





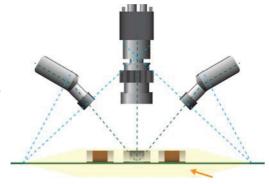


# The perfect combination of 3D and 2D inspection

Height, tilt and coplanarity measurement. Pin Height measurement Component Presence Absence, Polarity, Value, Angle, Offset, Colour, Extra part detection, Solder ball detection, Solder profile analysis and short detection. The thickness of chip capacitors in combination with colour makes a more reliable inspection when checking chip capacitors value.

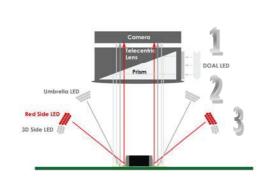
### **Unique 3D Stereoscopic Vision**

Utilizing the full 9 cameras of the MEK camera head. The image differential are merged and a vectorised map of the component is created. Then analyzed based on the programmers applied tolerances. The vectorised map of the components removes the minor imperfection of the component surface giving more accurate measurement of height and surface angle of the component with reduced chance of false readings.



### Omnidirectional multi angle, multi color LED lighting

Optimal light no matter component direction — 3D color profile of solder meniscus — Reliable defect decision by the software — Decide Good Solder, No Solder, Lack of Solder and Too much solder for SMT and THT solder joints

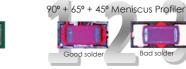












### 8x Angular Side Sensors (Only available for FDA and FDAz models)

Simultaneously operating, multiplexed side view sensors with CameraLink interface -45/45 arrangement - Triple use: Active automatic inspection, classification and repair — clear 9 angles defect review — high magnification 50x (10µm/pixel) — Full Color — Auto highlight — Large sensor pixels — 9 view images also in backup database



# Enwertpectar GTAZ

# Hardware and Software Features — Continued

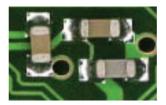
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# Double size FOV (Field of view)

Up to 2x faster inspection over previous generations of machines. Square FOV combined with circular lighting allows for program rotation without time consuming debugging.

# Large pixel image capturing sensor

18.8µm² pixel size — less noise — smooth and detailed image— great dynamic range





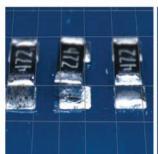
High dynamics sensor

Conventional sensor

# In Height Adjustable Optical Head

In Z-Axis moving Top Camera, Light and Side View cameras — Adaption to any PCB Thickness — PCB Warp Compensation — Inspection of PCB's with very tall components — Reliable text and/or polarity inspection on tall components Inspection of "Sandwich" assemblies without need of jigs and multiple inspections



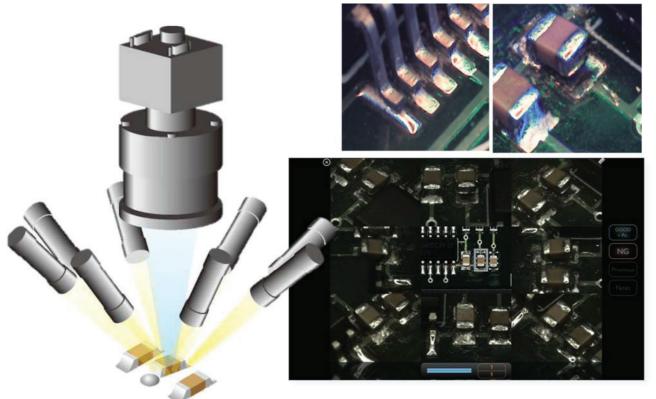




Shift & Tilt Side View lenses

Distortion free side images across whole FoV. Every point on the PCB within the FoV has same distance to the capturing sensor despite the angle of the optics

Without Shift&Tilt Shift&Tilt





# **Inline**

# Enwertpectar

**GTAz** 

350L, 650L, 800L

In-Line Series Specifications	PowerSpector GTAz 350L	PowerSpector GTAz 650L	PowerSpector GTAz 800L
Maximum PCB Size	350x250mm (13.8"x9.8")	650x550mm (25.6"x21.6")	800x550mm (31.5"x21.6")
Characteristics			
Product type	Automatic Optical Inspector		
In-line/Off-line	In-Line		
Camera movement	X + Y Direction		
PCB movement	Stationary during inspection		
Parts inspection	Presence, Polarity, Offset, Correctness, Soldering, Height		
Printing/paste inspection	Offset, Smearing, Bridges, Uniformity		
Image Processing	Synthetic Imaging, Spectral Analysis, Greyscale limits		
Image Parameters	Brightness, Hue, Saturation via Filters		
Camera type	Digital color Thunderbolt interface 90 Fps		
Camera Field Of View/Resolution	38.5x38.5mm/18.75µm or 19.5x19.5mm/10µm		
Lens	Telecentric lens with built in prism for DOAL Lighting		
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Lighting system	Omnidirectional T Quad LED rings: Side White, Side Red, Main, Line Sourced DOAL (Diffused On Axis Lighting (Coaxial))		
Specifications	,		· · ·
Minimum inspection component size	01005" (0.4x0.2mm)(10µm resolution)		
Positioning accuracy	Pixel related Feedback Loop		
Component clearance (top)	30mm (1.2")		
Side Cameras	8x Digital color USB 3.0 Vision in 45/45 orientation		
Z-Axis movement range	30mm (1.2")		
Component clearance (bottom)	35mm (1.38") or 55mm (2.17") without PCB support lift option		
Maximum PCB Size	350x250mm (13.8" x 9.8")   650x550mm (25.6" x 21.6")   800x550mm (31.5"x21.6")		
Movement speed	720mm/s		
Inspection capacity typical	2750ppm		
Electrical requirements		100-240 VAC / 330W	
Conveyor			
Conveyor belt speed	10-500mm/s (0.4-19.7"/s)		
Conveyor configuration	Left>Right, Front rail fixed, Height 830-950mm  Top Justified, Ruler Blade, Top & Edge Clamping, Sensor Stopper		
PCB Clamping Minimum board size	50x50mm (2.0" x 2.0")		
	0.6-2mm (option 0.6-4mm) (24mils - 79mils)		
Board thickness	Automatic PCB support Lift with magnetic pins (option)		
PCB warpage compensation  Interfacing		b support Lift with magneti	c pins (opilon)
Control PC type	Apple Mac Mini or iMac		
Control interface	SMEMA (conveyer)		
Data interface	USB and Thunderbolt		
Programming Interface	CSV Centroid file (Placement file)		
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windows 7/8/10) (option)		
3rd party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)		
General	i i	DI VIAIT LIIES SOCKEL (COICI	
	15 30 dea C/40 90 dea El		
Operating temperature	15-30 deg. C(60-90 deg. F)		
Operating humidity	15-80 % RH		
External size	W740 x D786 x H1236 (29.1" x 30.9" x 48.7")	W1040 x D1077 x H1270 (40.9" x 42.4" x 50.0")	W1190 x D1077 x H1259 (46.9" x 42.4" x 49.5")
Weight	180kg (397lbs)	240kg (529lbs)	290kg (639lbs)

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